ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®	© Co	terial Compo pyright 2005. IPC, Bannoc International and Pan-Americ	kburn, Illinois	. All rights reserv	tion with lower	level p	arts, the	declaratior	n encor	mpasses all l		erials for	which	ne item is an assembly the manufacturer has declaration.
1752-2 1.1		Web Site for Informat	ard	Form Type * Distribute			Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informa							
Supplier Information														
Company Name * Company Unique ID				Unique ID Authority			Response Date *			Response D				
Semtech Corporation		SEMTECH CORPOR	RATION		2017-03-30									
Contact Name *		Title - Contact		Phone - Cor	Email - Contact *						A (1			
Jeffrey Gabrielson		QA Customer Suppo	rt Specialis	805-498-2111		jgabrielson@semtech.com			om	Duplic	ate Contact	-> Autho	prized R	epresentative
Authorized Representative *		Title - Representative	Э	Phone - Representative *		Email - Representative *		*	Supplier Co	mments or UR	L for Add	ditional	Information	
Jeffrey Gabrielson		QA Customer Suppo	ort Speciali	805-498-211	jgabrielson@semtech.com			om						
Requester Item Number	er	Mfr Item Number		Mfr Item Name	Effectiv	e Date	Version	Manufa	acturing Site	Weight *	UC	M	Unit Type	
	SX8644I05AWLTRT			ULTRA LOW POWER, CAPAC			Mala			/sia 0.05645		mg	3	Each
Alternate Recommend	lation				Alternat		Alternate	Item Co	omments			-		
Manufacturing Proce	ss In	formation												
Terminal Plating / Grid Array	Materi	ial	Terminal Ba	ase Alloy	J-STD-020 MSL Ra	ting	Peak Proc	ess Body	Temper	ature Max Ti	me at Peak Tem	perature	Number	r of Reflow Cycles
Tin (Sn) CU Alloy			2			260			;	<b>30</b> s	econds	3		
Comments SX8644I05AWLTRT is R	EACH	I-compliant product	, per EU R	egulation E	C1907/2006 to inc	lude re	ecent add	lition of S	SVHC (	candidate li	st of substand	ces in Fe	ebruary	v 2017.

Save the fields in this form to a file	Evport Data	Import fields from a file into this form	Import Data	Clear all of the fields on this form	Reset Form	Lock the fields on this form to prevent chan	Look Cupplier Fields				
RoHS Material Composition Declaration Declaration Declaration Type *											
		ty limit of 0.1% by mass (100 Ethers (PBDE) and quantity					ominated Biphenyls (PBB),				
chromium, polybromina excess of an applicable gathered the information Company will rely on thi completing this form, ar certifications regarding conditions of that agree	ted biphenyls and/or polybrominate quantity limit, please indicate below it provides in this form using app s certification in determining the co d that Supplier may not have inde heir contributions to the part, and ment, including any warranty rights	ompliance of its products with European pendently verified such information. Ho those certifications are at least as comp	ricted substance?) in excess believe may apply. If the p y and that such information n Union member state laws owever, in situations where prehensive as the certificati hat agreement, will be the s	ss of the applicable quantity lim part is an assembly with lower I is true and correct to the best of that implement the RoHS Dire Supplier has not independently ion in this paragraph. If the Co sole and exclusive source of the	it identified above. If a homoge evel components, the declaration of its knowledge and belief, as of ctive. Company acknowledges y verified information provided lo popany and the Supplier enter is a Supplier?s liability and the Co	eneous material within the part cor on shall encompass all such comp of the date that Supplier complete: s that Supplier may have relied on by others, Supplier agrees that, at into a written agreement with resp impany?s remedies for issues that	ntains a RoHS restricted substance in ponents. Supplier certifies that it s this form. Supplier acknowledges that information provided by others in a minimum, its suppliers have provided				
RoHS Declaration	n * 1 - Item(s) does not conta	ain RoHS restricted substances per the	he definition above			Supplier Acceptance *	Accepted				
	e declared item does not co all applicable exemptions.	ntain RoHS restricted substanc	es per the definition a	above except for defined	RoHS exemptions, then	select the corresponding re	esponse in the RoHS Declaration				
Declaration S	ignature										
In a family of the second	ward a factor and the factor of the second s	al Calaba and all manages of the last		a second se	• • • • •	and the second s	terrestring and - Distingthe stars				

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

## Homogeneous Material Composition Declaration for Electronic Products

Subltem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

	Item/SubItem		Homogeneous	Weight	Unit of		Leve	Substance Catego			Substance	CAS	Exempt			Tolerance		PPM
	Name		Material	weight	Measure		Leve	Substance Categor	y		Substance	CAS	Exempt	weight	Measure	-	+	FFIVI
+  -	Die	+М -М	Silicon Chip	0.0019	mg	+C -	C Supp	er	+S	-S	Si	7440-21-3		0.0019	mg		-	33,660
+  -	Lead Frame	+M -M	Ag Plated Cu C1	0.03312	mg	+C -	C Supp	er	+S	-S	Cu	7440-50-8		0.03199	mg			13,237
									+S	5 -S	Fe	7439-89-6		0.00075	mg			17.6
						+C -	CA		+S	5 -S	Lead	7439-92-1		0	mg			140.82
						+C -	C Supp	er	+S	-s	Р	7723-14-0		0.00001	mg		-	745.18
								•	+S	6 -S	Zn	7440-66-6		0.00004	mg			5,867.5
									+8	6 -S	Ag	7440-22-4		0.00033	mg			33,660
+  -	Die attach material	+M -M	Conductive epox	0.00082	mg	+C -	C Supp	er	+S	-s	Silver	7440-22-4		0.00066	mg			11,694
			-				-		+S	-s	Carbocycllic Acrylate	Proprietary		0.00008	mg			1,452.7
									+S	5 -S	Bismaleimide resin	Proprietary		0.00002	mg			435.81
									+S	-s	2-preponoic acid, 2-met	68586-19-6		0.00002	mg			435.81
									+S	5 -S	Additive	Proprietary		0.00002	mg			435.81
									+S	5 -S	Dicumlyl peroxide	80-43-3		0.000004	Img			72.64
+  -	Wire	+M -M	Gold	0.00072	mg	+C -	C Supp	er	+S	-s	Au	7440-57-5		0.000719	mg			12,754
			-				-		+S	-s	Others	N/A		0.00000	Img			1.28
+  -	Lead Finsish	+M -M	Alloy	0.00033	Smg	+C -	C Supp	er	+S	-s	Sn	7440-31-5		0.000336	mg		ļ	5,952
							•		+S	-s	Others	N/A		0.00000	Img			0.6
+  -	Encapsulation	+M -M	EME-G770HCD	0.01955	mg	+C -	C Supp	er	+S	-S	Silica Fused	60676-86-0		0.018318	mg	· [	Ţ.	324,52
							_		+S	5 -S	Epoxy Resin	Proprietary		0.000587	mg			10,390
									+S	5 -S	Phenol Resin	Proprietary		0.03905	mg			10,390
									+S	5 -S	Carbon Black	1333-86-4		0.000059	mg			1,039.0